

**AMENDMENTS TO THE CLAIMS**

Claims 1-25 Cancelled without prejudice or disclaimer.

26. Previously Withdrawn from Appeal

27. Previously Withdrawn from Appeal

28. Previously Withdrawn from Appeal

29. Previously Withdrawn from Appeal

Claims 30-37 Cancelled without prejudice or disclaimer.

Claims 38-44 Previously cancelled without prejudice or disclaimer.

Claims 45-58 Cancelled without prejudice or disclaimer.

59. (Original) An imaging device comprising:  
an image sensor subassembly including an image sensor mounted on a printed circuit board;  
a substantially rigid optical subassembly, said optical subassembly including an optical element disposed on a substantially rigid member;  
at least one solderable surface formed on either of said printed circuit board or said optical subassembly defining at least one solder receiving interface between said printed circuit board and said optical subassembly; and  
solder material for bonding said subassemblies disposed at said at least one solder-receiving interface.

60. (Original) The device of claim 59, further including a housing encapsulating said device, said device partially defining a feed path.

61. (Original) The device of claim 59, further including a housing encapsulating said device, said housing including a handle.

62. (Original) The device of claim 59, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

63. (Original) The device of claim 59, wherein said at least one solderable surface is made in the configuration of a hole.

64. (Original) The device of claim 59, wherein said at least one solderable surface is in the configuration of a pin.

65. (Original) The device of claim 59, wherein said at least one solderable surface is provided by a threaded screw.

66. (Original) An imaging device comprising:  
an image sensor subassembly including an image sensor mounted on a printed circuit board;  
a substantially rigid optical subassembly, said optical subassembly having a single receive optical axis and including an optical element disposed on a substantially rigid member;  
at least one solderable surface formed on either of said image sensor subassembly or optical subassembly defining at least one solder receiving interface between said image sensor subassembly and said optical subassembly; and  
solder material for bonding said subassemblies disposed at said at least one solder-receiving interface.

67. (Original) The device of claim 66, further comprises a housing encapsulating said device said housing partially defining a feed path for receiving documents.

68. (Original) The device of claim 66, further comprising a housing encapsulating said device said housing including a handle.

69. (Original) The device of claim 66, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

70. (Original) The device of claim 66, wherein said at least one solderable surface is made in the configuration of a hole.

71. (Original) The device of claim 66, wherein said at least one solderable surface is in the configuration of a pin.

Claim 72 Cancelled without prejudice or disclaimer.

73. (Original) An optical reading device comprising:  
an optical and image sensor assembly including  
an image sensor subassembly including an image sensor mounted on a substantially rigid planar member,  
an optical subassembly, said optical subassembly including an optical element disposed on a substantially rigid member,  
at least one solderable surface formed on either of said optical subassembly or said substantially rigid planar member defining at least one solder receiving interface between said substantially rigid planar member and said optical subassembly,  
solder material for bonding said subassemblies disposed at said at least one solder-receiving interface,  
a housing, said optical and image sensor assembly being disposed in said housing.

74. (Original) The device of claim 73, wherein said housing partially defines a feed path and wherein said device is a document reading device, for reading indicia from documents transported along said feed path.

75. (Original) The device of claim 73, wherein said housing includes a handle, and wherein said device is a hand held optical reader.

76. (Original) The device of claim 73, wherein said at least one solderable surface is made in an irregular configuration having an increased surface area per unit three dimensional space relative to that of a smooth surface.

77. (Original) The device of claim 73, wherein said at least one solderable surface is made in the configuration of a hole.

78. (Original) The device of claim 73, wherein said at least one solderable surface is in the configuration of a pin.

79. (Original) The device of claim 73, wherein said at least one solderable surface is provided by a threaded screw.

Claims 80-108 Cancelled without prejudice or disclaimer.